



Specification for Approval

Date: 2023/6/6







宏業興 **Customer:**

TAI-TECH P/N:

	TAI-TECH P/N:	FCM3216HF-102T03						
	CUSTOMER P/N:							
	DESCRIPTION:							
	QUANTITY:	pcs						
REI	MARK:							
	Cu	stomer Approval Feedback						
	二 十 章	电 彩 怯 肌 心 方 阳 心 习						

西 北 臺 慶 科 技 股 份 有 限 公 可 TAI-TECH Advanced Electronics Co., Ltd

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R&D Center

APPROVED	CHECKED	DRAWN
鄧福興	浦冬生	王俞琴

Ferrite Chip Bead(Lead Free)

FCM3216HF-102T03

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAW
1.0	13/06/06	變更可靠度條件	楊祥忠	羅培君	張嘉珍
2.0	14/01/24	變更電鍍錫層厚度 3.0um min.=>3.5um min.	楊祥忠	羅培君	張嘉琦
3.0	14/08/01	變更 Reflow 圖示	楊祥忠	羅培君	張嘉玓
3.1	14/08/01	修正包裝帶尺寸	楊祥忠	羅培君	張嘉环
4.0	16/01/26	增訂可靠度 Thermal shock: (Bead) Step3:125±2℃ 30±5min	楊祥忠	詹偉特	張嘉环
5.0	17/02/16	修訂 Recommended PC Board Pattern	楊祥忠	詹偉特	張嘉玹
6.0	20/08/01	更新 Reflow 依 IPC EDEC J-STD-020E	鄧福興	浦冬生	王俞琴
7.0	22/12/05	更新可靠度及更正 Reflow 敘述	鄧福興	浦冬生	王俞琴
備			•		

TAI-TECH KBM01-230600173 P2.

Ferrite Chip Bead(Lead Free)

FCM3216HF-102T03

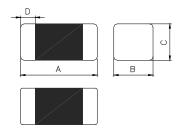
Certificate

Green Partner

1.Features

- 1. Monolithic inorganic material construction.
- 2. Closed magnetic circuit avoids crosstalk.
- 3. S.M.T. type.
- 4. Suitable for reflow soldering.
- 5. Shapes and dimensions follow E.I.A. spec.
- 6. Available in various sizes.
- 7. Excellent solder ability and heat resistance.
- 8. High reliability.
- 9.100% Lead(Pb) & Halogen-Free and RoHS compliant.

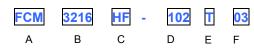
2. Dimensions



Chip Size				
A 3.20±0.20				
В	1.60±0.20			
С	1.10±0.20			
D	0.50±0.30			

Units: mm

3.Part Numbering



A: Series

B: Dimension

C: Material

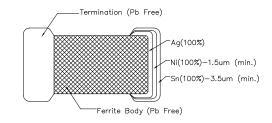
D: Impedance

E: Packaging F: Rated Current

L x W Lead Free Material

102=1000 Ω

T=Taping and Reel, B=Bulk(Bags)

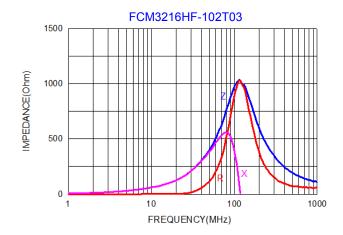


4.Specification

Tai-Tech Part Number		Impedance (Ω)	Test Frequency (Hz)	DC Resistance (Ω) max.	Rated Current (mA) max.
	FCM3216HF-102T03	1000±25%	60mV/100M	0.60	300

- Rated current: based on temperature rise test
- In compliance with EIA 595

■ Impedance-Frequency Characteristics



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TAI-TECH KBM01-230600173 P3.

5. Reliability and Test Condition

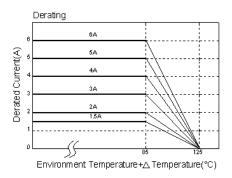
Item		Performance				Tes	st Cond	dition	
Series No.	FCB FCM	НСВ	GHB	FCA					
Operating Temperature	(Inclu	-55~+125℃ ding self-temperato	ure rise)						
Transportation Storage Temperature	-55~+125℃ (on board)					For long storage conditions, please see the Application Notice			
Impedance (Z)	Defects standard classical	shara storiotica list			Agilent42 Agilent E Agilent42 Agilent16	4991 287			
DC Resistance	Refer to standard electrical of	maracteristics list			Agilent 4				
Rated Current					DC Power Over Rat some risk	ed Curr		ements, the	re will be
Temperature Rise Test	Rated Current < 1A ∆T 20℃Max Rated Current ≧ 1A ∆T 40℃Ma	Rated Current < 1A Δ T 20 $^{\circ}$ Max Rated Current \geq 1A Δ T 40 $^{\circ}$ Max					owed DC neasured	current. by digital su	urface
Life test	Appearance: no damage.				times.(IF Reflow P Tempera Applied of Duration: Measure for 24±2	PC/JEDI Profiles) ture: 12 current: : 1000±1 d at roo hrs.	EC J-STD 5±2℃ rated curn 12hrs. om tempe	erature after	sification
Load Humidity	Impedance: within±15%of initial value. RDC: within ±15% of initial value and shall not exceed the specification value				Humidity: 85±2%R.H. Temperature: 85±2°C. Duration:1000hrsMin.Bead:with100%ratedcu ent inductance: with 10% rated curre Measured at room temperature after placin				ratedcurr current
Thermal shock	Appearance: no damage. Impedance: within±15%of ini RDC: within ±15% of initial		for 24±2 hrs Preconditioning: Run through reflow fo times.(IPC/JEDEC J-STD-020E Classifical Reflow Profiles) Condition for 1 cycle Step1: -55±2°C 30±5 min. Step2: 125±2°C 30±5 min. Step3: 125±2°C 30±5 min. Number of cycles: 500 Measured at room temperature after place for 24±2 hrs.				sification		
Vibration	Appearance: No damage. Impedance: within±15% of initial value RDC: within ±15% of initial value and shall not exceed the specification value				Preconditioning: Run through reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Oscillation Frequency: 10Hz ~ 2KHz ~ 10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:10g Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations)				
Bending	Appearance: No damage. Impedance: within±10% of i RDC: within±15% of initial		exceed the spe	cification value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805inch(2012mm):40x100x1.2mm <0805inch(2012mm):40x100x0.8mm Bending depth: >=0805inch(2012mm):1.2mm <0805inch(2012mm):0.8mm Duration of 10 sec for a min.				
					Test cor	ndition:			
Shock	Appearance: No damage. Impedance: within±10% of i				Туре	Peak Value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec
	RDC: within ±15% of initial	value and shall not	exceed the spe	cification value	SMD	50	11	Half-sine	11.3
					Lead a Method	50	11 4 hrs (Half-sine	11.3
Solderability	More than 95% of the termina	al electrode should	be covered with	ı solder.	@235°C: b. Metho ± 15 min	±5°C Te d D cat)@ 260°	st time:5 -	@155°C d ⊦0/-0.5 seco steam agino nds.	onds.

TAI-TECH KBM01-230600173 P4.

Item	Performance	Test Condition				
		Number of heat	Number of heat cycles: 1			
Resistance to Soldering	Appearance : No damage.	Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate		
Heat	Impedance: within±15% of initial value RDC: within±15% of initial value and shall not exceed the specification	on value	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	
			Depth: completely cover the termination			
Terminal strength	Impedance: within±15% of initial value RDC: within±15% of initial value and shall not exceed the specification value	wide thickness shear force	Preconditioning: Run through reflow for times.(IPC/JEDEC J-STD-020E Classificatio Reflow Profiles) Component mounted on a PCB apply a forc >0805inch(2012mm):1kg <=0805inch(2012mm):0.5kg to the side of a device being tested. This forc shall be applied for 60 +1 seconds. Also th force shall be applied gradually as not to shoc the component being tested.			

**Derating Curve

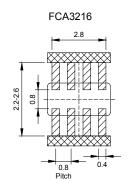
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over $85^{\circ}\mathrm{C}$, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



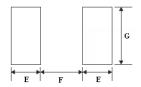
6. Soldering and Mounting

6-1. Recommended PC Board Pattern

	Chip Size							s For ering
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
FCB	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	0.50	0.40	0.60
FCM	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95
нсв	2012	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	1.05	1.05	1.45
GHB	2012	2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30			
FCI	<mark>3216</mark>	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	<mark>1.05</mark>	<mark>2.20</mark>	<mark>1.80</mark>
FHI	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	1.05	2.20	2.70
FCH	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	1.05	3.30	1.80
HCI	4532	4.5±0.20	3.20±0.20	1.50±0.20	0.50±0.30	1.05	3.30	3.40



Land
Solder Resist



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

6-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

TAI-TECH KBM01-230600173 P5.

6-2.1 Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

6-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C • 350°C tip temperature (max)
- Never contact the ceramic with the iron tip • 1.0mm tip diameter (max)
- · Use a 20 watt soldering iron with tip diameter of 1.0mm
- · Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow

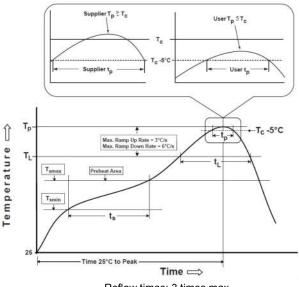
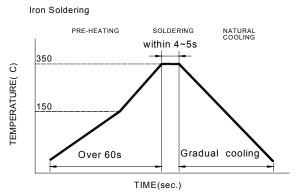


Fig.2 Iron soldering temperature profiles



Iron Soldering times: 1 times max

Reflow times: 3 times max

Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
$eq:continuous_continuous$	150°C 200°C 60-120seconds
Ramp-up rate(T _L to T _p)	3℃/second max.
Liquidus temperature(T _L) Time(t _L)maintained above T _L	217℃ 60-150 seconds
Classification temperature(T _c)	See Table (1.2)
$Time(t_p)$ at Tc- $5^{\circ}\mathbb{C}$ (Tp should be equal to or less than Tc.)	< 30 seconds
Ramp-down rate(Tp to TL)	6℃ /second max.
Time 25℃ to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, Tc: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc**.

Table (1.2) Package Thickness/Volume and Classification Temperature (Tc)

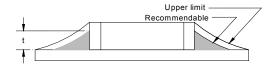
	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
	<1.6mm	260°C	260°C	260°C
PB-Free Assembly	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E -

6-2.3 Solder Volume:

Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

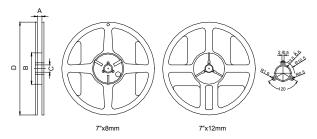
Minimum fillet height = soldering thickness + 25% product height



TAI-TECH KBM01-230600173 P6.

7.Packaging Information

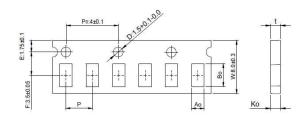
7-1. Reel Dimension



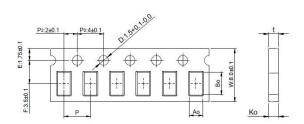
Type		A(mm)	B(mm)	C(mm)	D(mm)
	<mark>7"x8mm</mark>	9.0±0.5	<mark>60±2</mark>	13.5±0.5	<mark>178±2</mark>
	7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2

7-2.1 Tape Dimension / 8mm

■Material of taping is paper

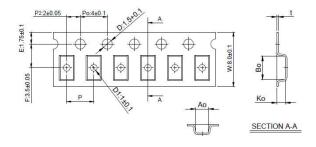


Ī	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	
	100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03	



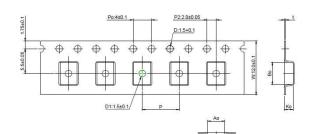
Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
160808	1.80±0.05	0.96+0.05/-0.03	0.95±0.05	4.0±0.10	0.95±0.05
201209	2.10±0.05	1.30±0.05	0.95±0.05	4.0±0.10	0.95±0.05

■Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
201212	2.10±0.10	1.28±0.10	1.28±0.10	4.0±0.10	0.22±0.05	1.0±0.10
<mark>321611</mark>	3.35±0.10	1.75±0.10	<mark>1.25±0.10</mark>	4.0±0.10	0.23±0.05	1.0±0.10
322513	3.42±0.10	2.77±0.10	1.55±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321609	3.40±0.10	1.77±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

7-2.2 Tape Dimension / 12mm



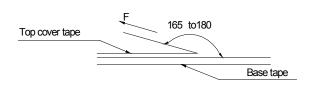
Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.10	0.24±0.05	1.5±0.10
453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.10	0.24±0.05	1.5±0.10

TAI-TECH KBM01-230600173 P7.

7-3. Packaging Quantity

Chip Size	453215	451616	322513	<mark>321611</mark>	321609	201212	201209	160808	100505
Chip / Reel	1000	2000	2500	<mark>3000</mark>	3000	2000	4000	4000	10000
Inner box	4000	8000	12500	<mark>15000</mark>	15000	10000	20000	20000	50000
Middle box	20000	40000	62500	<mark>75000</mark>	75000	50000	100000	100000	250000
Carton	40000	80000	125000	<mark>150000</mark>	150000	100000	200000	200000	500000

7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

Application Notice

Storage Conditions(component level)

To maintain the solder ability of terminal electrodes:

- 1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
- 3. Recommended products should be used within 12 months from the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.





Test Report

號碼(No.): ETR22B04558

日期(Date): 06-Dec-2022

頁數(Page): 1 of 15

西北臺慶科技股份有限公司 (TAI-TECH ADVANCED ELECTRONICS CO., LTD.)

臺慶精密電子(昆山)有限公司 (TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

慶邦電子元器件 (泗洪) 有限公司 (TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN R. O. C.)

江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 (GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

中國·江蘇省·宿遷市·泗洪縣·經濟開發區杭州路南側·建設北路東側 (THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD · ECONOMIC DEVELOPMENT ZONE · SIHONG COUNTY · SUQIANCITY · JIANGSU PROVINCE · P.R · CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by the applicant as):

樣品名稱(Sample Name) : FERRITE CHIP BEAD、FERRITE CHIP INDUCTOR、ARRAY、MCF、MCM、

YMV SERIES

樣品型號(Style/Item No.) : FERRITE CHIP BEAD、FERRITE CHIP INDUCTOR、ARRAY、MCF、MCM、

YMV SERIES

收件日(Sample Receiving Date) : 29-Nov-2022

測試期間(Testing Period) : 29-Nov-2022 to 06-Dec-2022

測試需求(Test Requested) : 依據客戶要求進行測試,測試項目請參閱測試結果表格。(Testing item(s) is/are

specified by client. Please refer to result table for testing item(s).)

測試結果(Test Results) : 請參閱下一頁 (Please refer to following pages.)

Troy Chang / Department Mayager
Signed for and on behalf of Alwan
SGS TAIWAN LTD.
Chemical Laboratory - Taipei



PIN CODE: 4545AB9D



Test Report

號碼(No.): ETR22B04558 日期(Date): 06-Dec-2022

頁數(Page): 2 of 15

西北臺慶科技股份有限公司 (TAI-TECH ADVANCED ELECTRONICS CO., LTD.)

臺慶精密電子(昆山)有限公司 (TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

慶邦電子元器件 (泗洪) 有限公司 (TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN R. O. C.)

江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 (GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

中國·江蘇省·宿遷市·泗洪縣·經濟開發區杭州路南側·建設北路東側 (THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD · ECONOMIC DEVELOPMENT ZONE · SIHONG COUNTY · SUQIANCITY · JIANGSU PROVINCE · P,R · CHINA)

測試部位敘述 (Test Part Description)

No.1 : 整體混測 (MIXED ALL PARTS)

測試結果 (Test Results)

測試項目	測試方法	單位	MDL	結果
(Test Items)	(Method)	(Unit)		(Result)
				No.1
鎘 (Cd) (Cadmium (Cd)) (CAS No.: 7440-	參考IEC 62321-5: 2013 · 以感應耦合電漿發射光	mg/kg	2	n.d.
43-9)	譜儀分析。(With reference to IEC 62321-5:			
	2013, analysis was performed by ICP-OES.)			
鉛 (Pb) (Lead (Pb)) (CAS No.: 7439-92-1)	參考IEC 62321-5: 2013·以感應耦合電漿發射光	mg/kg	2	n.d.
	譜儀分析。(With reference to IEC 62321-5:			
	2013, analysis was performed by ICP-OES.)			
汞 (Hg) (Mercury (Hg)) (CAS No.: 7439-	參考IEC 62321-4: 2013+ AMD1: 2017,以感應耦	mg/kg	2	n.d.
97-6)	合電漿發射光譜儀分析。(With reference to IEC			
	62321-4: 2013+ AMD1: 2017, analysis was			
	performed by ICP-OES.)			
六價鉻 Cr(VI) (Hexavalent Chromium	參考IEC 62321-7-2: 2017,以紫外光-可見光分光	mg/kg	8	n.d.
Cr(VI)) (CAS No.: 18540-29-9)	光度計分析。(With reference to IEC 62321-7-2:			
	2017, analysis was performed by UV-VIS.)			



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測試項目	測試方法	單位	MDL	結果
(Test Items)	(Method)	(Unit)		(Result)
				No.1
一溴聯苯 (Monobromobiphenyl)		mg/kg	5	n.d.
二溴聯苯 (Dibromobiphenyl)		mg/kg	5	n.d.
三溴聯苯 (Tribromobiphenyl)		mg/kg	5	n.d.
四溴聯苯 (Tetrabromobiphenyl)		mg/kg	5	n.d.
五溴聯苯 (Pentabromobiphenyl)		mg/kg	5	n.d.
六溴聯苯 (Hexabromobiphenyl)		mg/kg	5	n.d.
七溴聯苯 (Heptabromobiphenyl)		mg/kg	5	n.d.
八溴聯苯 (Octabromobiphenyl)		mg/kg	5	n.d.
九溴聯苯 (Nonabromobiphenyl)		mg/kg	5	n.d.
十溴聯苯 (Decabromobiphenyl)	參考IEC 62321-6: 2015·以氣相層析儀/質譜儀分	mg/kg	5	n.d.
多溴聯苯總和 (Sum of PBBs)	参与IEC 02321-0. 2013,以無相層和嚴/真語儀力 析。(With reference to IEC 62321-6: 2015,	mg/kg	-	n.d.
一溴聯苯醚 (Monobromodiphenyl ether)	analysis was performed by GC/MS.)	mg/kg	5	n.d.
二溴聯苯醚 (Dibromodiphenyl ether)	analysis was performed by GC/1813.)	mg/kg	5	n.d.
三溴聯苯醚 (Tribromodiphenyl ether)		mg/kg	5	n.d.
四溴聯苯醚 (Tetrabromodiphenyl ether)		mg/kg	5	n.d.
五溴聯苯醚 (Pentabromodiphenyl ether)		mg/kg	5	n.d.
六溴聯苯醚 (Hexabromodiphenyl ether)		mg/kg	5	n.d.
七溴聯苯醚 (Heptabromodiphenyl ether)		mg/kg	5	n.d.
八溴聯苯醚 (Octabromodiphenyl ether)		mg/kg	5	n.d.
九溴聯苯醚 (Nonabromodiphenyl ether)		mg/kg	5	n.d.
十溴聯苯醚 (Decabromodiphenyl ether)		mg/kg	5	n.d.
多溴聯苯醚總和 (Sum of PBDEs)		mg/kg	-	n.d.



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測試項目	測試方法	單位	MDL	結果
(Test Items)	(Method)	(Unit)		(Result)
				No.1
鄰苯二甲酸丁苯甲酯 (BBP) (Butyl benzyl		mg/kg	50	n.d.
phthalate (BBP)) (CAS No.: 85-68-7)				
鄰苯二甲酸二丁酯 (DBP) (Dibutyl		mg/kg	50	n.d.
phthalate (DBP)) (CAS No.: 84-74-2)				
鄰苯二甲酸二(2-乙基己基)酯 (DEHP) (Di-		mg/kg	50	n.d.
(2-ethylhexyl) phthalate (DEHP)) (CAS				
No.: 117-81-7)				
鄰苯二甲酸二異丁酯 (DIBP) (Diisobutyl		mg/kg	50	n.d.
phthalate (DIBP)) (CAS No.: 84-69-5)				
鄰苯二甲酸二異癸酯 (DIDP) (Diisodecyl	參考IEC 62321-8: 2017,以氣相層析儀/質譜儀分	mg/kg	50	n.d.
phthalate (DIDP)) (CAS No.: 26761-40-	析。(With reference to IEC 62321-8: 2017,			
0, 68515-49-1)	analysis was performed by GC/MS.)			
鄰苯二甲酸二異壬酯 (DINP) (Diisononyl	analysis was performed by GC/1813.)	mg/kg	50	n.d.
phthalate (DINP)) (CAS No.: 28553-12-				
0, 68515-48-0)				
鄰苯二甲酸二正辛酯 (DNOP) (Di-n-octyl		mg/kg	50	n.d.
phthalate (DNOP)) (CAS No.: 117-84-0)				
鄰苯二甲酸二正戊酯 (DNPP) (Di-n-		mg/kg	50	n.d.
pentyl phthalate (DNPP)) (CAS No.:				
131-18-0)				
鄰苯二甲酸二正己酯 (DNHP) (Di-n-hexyl		mg/kg	50	n.d.
phthalate (DNHP)) (CAS No.: 84-75-3)				



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測試項目 (Test Items)	測試方法 (Method)	單位 (Unit)	MDL	結果 (Result) No.1
六溴環十二烷及所有主要被辨別出的異構物(HBCDD) (α - HBCDD, β - HBCDD, γ - HBCDD) (Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α - HBCDD, β - HBCDD, γ - HBCDD)) (CAS No.: 25637-99-4, 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	參考IEC 62321-9: 2021.以氣相層析儀/質譜儀分析。(With reference to IEC 62321-9: 2021, analysis was performed by GC/MS.)	mg/kg	20	n.d.
氟 (F) (Fluorine (F)) (CAS No.: 14762-94-8)		mg/kg	50	n.d.
氯 (Cl) (Chlorine (Cl)) (CAS No.: 22537- 15-1)	参考BS EN 14582: 2016・以離子層析儀分析。		50	n.d.
溴 (Br) (Bromine (Br)) (CAS No.: 10097- 32-2)	(With reference to BS EN 14582: 2016, analysis was performed by IC.)	mg/kg	50	n.d.
碘 (I) (Iodine (I)) (CAS No.: 14362-44-8)		mg/kg	50	n.d.
全氟辛烷磺酸及其鹽類 (PFOS and its salts) (CAS No.: 1763-23-1 and its salts)	参考CEN/TS 15968: 2010 · 以液相層析串聯質譜 儀分析。(With reference to CEN/TS 15968:	mg/kg	0.01	n.d.
全氟辛酸及其鹽類 (PFOA and its salts) (CAS No.: 335-67-1 and its salts)	2010, analysis was performed by LC/MS/MS.)	mg/kg	0.01	n.d.
聚氯乙烯 (Polyvinyl chloride) (PVC)	參考ASTM E1252: 2021·以傅立葉轉換紅外線光 譜儀及焰色法分析。(With reference to ASTM E1252: 2021, analysis was performed by FT-IR and Flame Test.)	**	-	Negative

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測試項目	測試方法	單位	MDL	結果
(Test Items)	(Method)	(Unit)		(Result)
				No.1
銻 (Sb) (Antimony (Sb)) (CAS No.: 7440-		mg/kg	2	n.d.
36-0)	A 字UC FDA 20F2:1006 以咸咗细今雨坞祭射火			
砷 (As) (Arsenic (As)) (CAS No.: 7440-	參考US EPA 3052: 1996,以感應耦合電漿發射光 譜儀分析。(With reference to US EPA 3052:	mg/kg	2	n.d.
38-2)	1996, analysis was performed by ICP-OES.)			
鈹 (Be) (Beryllium (Be)) (CAS No.: 7440-	1 2 30, analysis was performed by ICF -OLS.)	mg/kg	2	n.d.
41-7)				

備註(Note):

- 1. mg/kg = ppm; 0.1wt% = 0.1% = 1000ppm
- 2. MDL = Method Detection Limit (方法偵測極限值)
- 3. n.d. = Not Detected (未檢出); 小於MDL / Less than MDL
- 4. "-" = Not Regulated (無規格值)
- 5. **= Qualitative analysis (No Unit) 定性分析(無單位)
- 6. Negative = Undetectable 陰性(未偵測到); Positive = Detectable 陽性(已偵測到)
- 7. 全氟辛烷磺酸及其鹽類包含等物質 (PFOS and its salts including): CAS No.: 1763-23-1, 2795-39-3, 29457-72-5, 29081-56-9, 70225-14-8, 56773-42-3, 251099-16-8, 307-35-7, 91036-71-4, 4021-47-0 and others.
- 8. 全氟辛酸及其鹽類包含等物質 (PFOA and its salts including): CAS No.: 335-67-1, 335-95-5, 2395-00-8, 335-93-3, 335-66-0, 3825-26-1 and others.
- 9. 樣品的測試是基於申請人要求混合測試‧報告中的混合測試結果不代表其中個別單一材質的含量。
 The sample(s) was/were analyzed on behalf of the applicant as mixing sample in one testing. The above result(s) was/were only given as the informality value.



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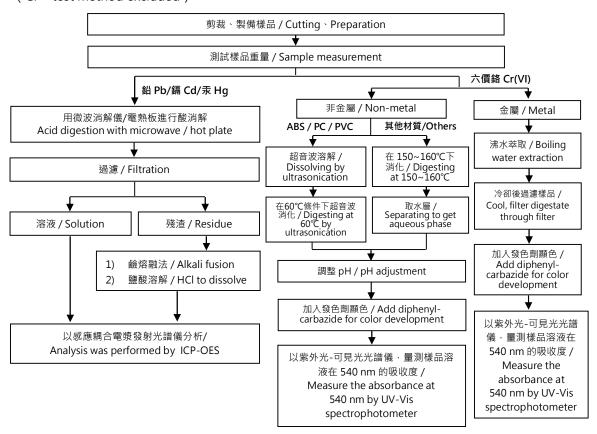
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重金屬流程圖 / Analytical flow chart of heavy metal

根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr^{6+} test method excluded)





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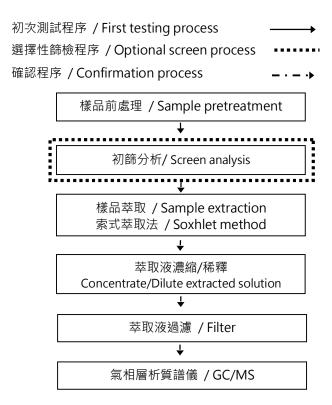
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多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBBs/PBDEs





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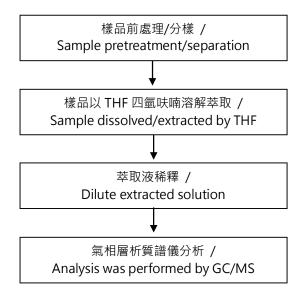
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可塑劑分析流程圖 / Analytical flow chart - Phthalate

【測試方法/Test method: IEC 62321-8】





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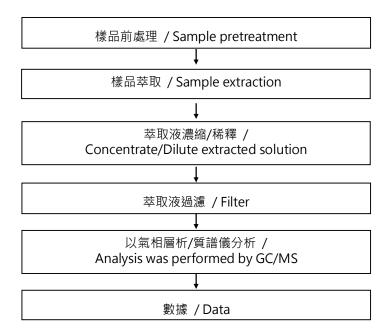
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六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD





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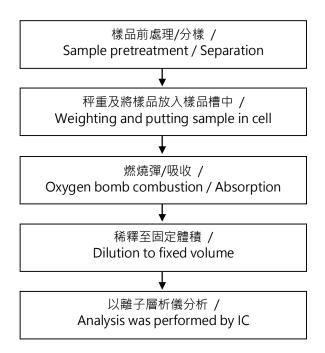
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鹵素分析流程圖 / Analytical flow chart - Halogen



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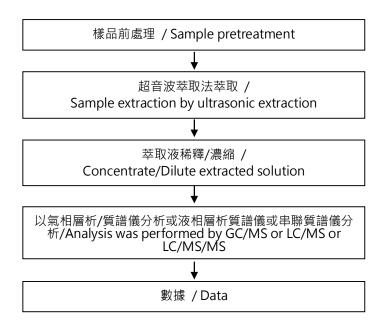
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全氟化合物(包含全氟辛酸/全氟辛烷磺酸/其相關化合物等等)分析流程圖 / Analytical flow chart – PFAS (including PFOA/PFOS/its related compound, etc.)



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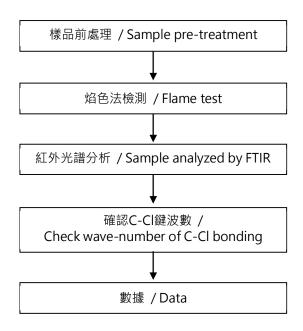
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聚氯乙烯物質判定分析流程圖 / Analysis flow chart - PVC





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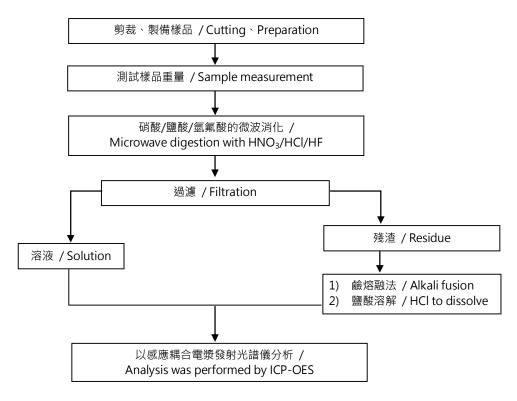
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元素(含重金屬)分析流程圖 / Analytical flow chart of elements (Heavy metal included)

根據以下的流程圖之條件,樣品已完全溶解。

These samples were dissolved totally by pre-conditioning method according to below flow chart.

【参考方法/Reference method: US EPA 3051A、US EPA 3052】



^{*} US EPA 3051A 方法未添加氫氟酸 / US EPA 3051A method does not add HF.



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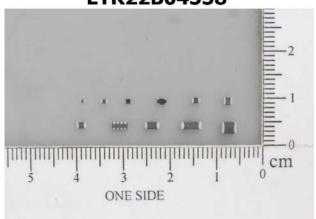
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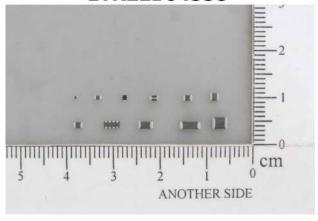
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* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. * (The tested sample / part is marked by an arrow if it's shown on the photo.)

ETR22B04558



ETR22B04558



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CZB2BFTTE601P 4221R-1 EMI0805R-600 SBY100505T-100Y-N NCB-GH0402D121TR060F NCB0402P301TR005F
NCB0603R152TR030F NCB0805A121TR050F NCB0805A301TR070F NCB3312K900TR500F NCB-H0805A221TR300F
NCB0402P221TR030F NCB0805A102TR040F NCB1806E151TR020F NCB-H0402P100TR200F NCB-H0603R121TR300F NCB-H0805A220TR600F NCB-H1206B601TR200F CZB1JGTTD202P CBH160808W221T WLBD1005HCU330TL WLBD2012HCU121TH
WLBD2012HCU221TH WQBD1608HCU121TH WLBD1608K2U252TB VLU0810-102KBC12 WLBD1608K2U800TP BMB2A0080AN4
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BBPY00160808301Y00 SBY100505T-750Y-N BBPY00100505102Y00